First developed by ESC back in 1999, this versatile deposition system is aimed at the research & development market. This flexible solution is easily configurable to meet the end users individual requirements.
Deposition Chamber Options

- Downwards or upwards sputtering
- RF, DC or Pulsed DC sputtering
- Evaporation, thermal or E-beam
- Ion beam assisted deposition for either sputtering or evaporation
- Reactive sputtering
- In process monitoring
- Turbo pump or cryo pump
- Wide range of round cathode sizes 2” up to 8”
- Up to five process gases, either chamber fed or at the cathode
- Substrate holder up to 8” round
- Substrate rotation
- Substrate heating
- Substrate bias RF or DC

Load Lock Options

- Low vacuum, backing pump only
- High vacuum, turbo pump or cryo pump
- Substrate RF etch
- Substrate heat
- Single substrate or multiple substrate
- Substrate holder up to 8” round